

~~10.~~ The assembly of claim 1 wherein the electronic device comprises an encapsulant layer.

~~11~~10. The assembly of claim 1 wherein the electronic device comprises an edge seal material.

~~12.~~ The assembly of claim 1 wherein the electronic device comprises a backsheet.

~~13~~11. The assembly of claim 1 wherein the multilayer film comprises a substrate between the electronic device and the barrier stack.

~~14.~~ The assembly of claim 1 wherein the electronic device comprises an encapsulant layer.

~~15~~12. The assembly of claim 10 wherein the edge seal material comprises butyl rubber.

~~16~~13. The assembly of claim ~~13~~11 wherein the substrate comprises at least one of polyethylene terephthalate, polyethylene naphthalate, polyetheretherketone, polyaryletherketone, polyacrylate, polyetherimide, polyarylsulfone, polyethersulfone, polyamideimide, or polyimide.

~~17~~14. The assembly of claim 1 wherein the weatherable sheet comprises a fluoropolymer.

~~18~~15. The assembly of claim ~~17~~14 wherein the fluoropolymer comprises at least one of an ethylene tetrafluoro-ethylene copolymer, a tetrafluoroethylene-hexafluoropropylene copolymer, a tetrafluoroethylene-hexafluoropropylene-vinylidene fluoride copolymer, or a polyvinylidene fluoride.

~~19~~16. The assembly of claim 1 comprising a pressure sensitive adhesive layer between the weatherable sheet and the barrier stack.

~~20~~17. The assembly of claim ~~19~~16 wherein the pressure sensitive adhesive is an acrylate, a silicone, a polyisobutylene, a urea or a blend thereof.

~~21~~18. The assembly of claim ~~19~~16 wherein the pressure sensitive adhesive comprises at least one of a UV stabilizer, a hindered amine light stabilizer, an antioxidant or a thermal stabilizer.

~~22~~19. The assembly of claim 1 wherein the barrier stack oxide layer shares a siloxane bond with the barrier stack polymer layer.

~~23~~20. The assembly of claim 1 wherein the electronic device is a photovoltaic cell.

~~24~~. — The assembly of claim ~~23~~ wherein the photovoltaic cell is a CIGS cell.

~~25~~21. The assembly of claim ~~13~~11 wherein the substrate is heat stabilized.

~~26~~22. The assembly of claim 1 wherein the barrier stack has a water vapor transmission rate of less than 0.005 cc/m²/day at 50°C and 100% relative humidity.

~~27~~23. The assembly of claim 1 wherein the barrier stack has an oxygen transmission rate of less than 0.005 cc/m²/day at 23°C and 90% relative humidity.

~~28~~24. The assembly of claim 1 wherein the barrier stack comprises at least two oxide layers.

~~29~~. — The assembly of claim 1 wherein the barrier stack comprises at least two polymers layers.

~~30. The assembly of claim 1 wherein the electronic device comprises a roof.~~

~~31~~25. The assembly of claim 7 wherein the opaque protective layer is in contact with the weatherable sheet and the barrier stack.